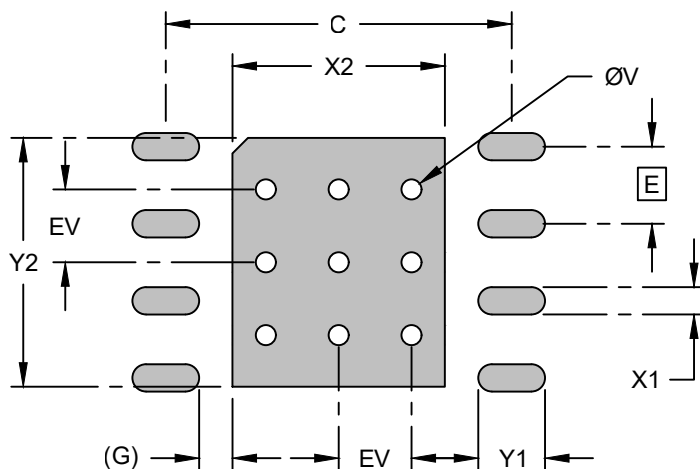


8-Lead Plastic Very, Very Thin Small Outline No-Lead (MF) - 6x5x0.8 mm Body [WSON] (Also Called WDFN)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packageing>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Optional Center Pad Width	X2			3.50
Optional Center Pad Length	Y2			4.10
Contact Pad Spacing	C		5.70	
Contact Pad Width (X20)	X1			0.45
Contact Pad Length (X20)	Y1			1.10
Contact Pad to Center Pad (X20)	(G)	0.55 (REF)		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. The theoretically exact value is shown without tolerances.
2. For best soldering results, please refer to the current industry standard IPC-7093.